

VERSION SHOWING AMENDMENT TO THE CLAIMS

This listing replaces all prior listings of the claims.

IN THE CLAIMS

Amend the claims as follows:

1 (Currently amended). A circuit board arrangement ~~or substrate~~ for an organic electronic device, comprising:

a circuit board having a surface on which a plurality of electrically interconnected electrical devices are disposed ~~substrate~~;

at least one of the electrical devices comprises an active organic electronic component electrically integrated on the substrate surface with others of the interconnected devices to form at least a portion of an electrical circuit,[[;]] the organic electronic component having at least one electrode layer;

the at least one electrode layer of the integrated active organic electronic component forming a conductive track layer on the surface of a base plate for an conventional inorganic semiconductor electrical component.

2 (Currently amended). A circuit board arrangement ~~or substrate~~ for an electronic device comprising:

a circuit board defining a surface ~~substrate~~; and

at least one active organic electrical component and at least one passive organic electrical component electrically interconnected and integrated to form at least a portion

of an electrical circuit on the surface substrate.

3 (Currently amended). The circuit board arrangement ~~or substrate~~ as claimed in claim 2, wherein the at least one active electrical component is one of an organic transistor, an organic diode, an organic photocell, an organic integrated circuit and/or the passive organic component is one of an electrically conducting connection, a resistor, a coil and/or a capacitor.

4 (Currently amended). The circuit board arrangement ~~or substrate~~ as claimed in one of the preceding claims including a power supply integrated with the electrical circuit on the substrate surface.

5 (Currently amended). The circuit board arrangement ~~or substrate~~ as claimed in any of claims 1 to 3 wherein an electrical input element and/or an electrical output element is electrically integrated with the circuit on the substrate surface.

6 (Currently amended). The circuit board ~~or substrate~~ arrangement as claimed in any of claims 1 to 3 wherein electrically conductive lines or conducting contacts are on the surface produced using structured conductive layers, electrodes such as source and drain electrodes and/or conductive adhesives and which may form electrodes for the electrical components.

7 (Currently amended). The circuit board ~~or substrate~~ arrangement as claimed in any of claims 1 to 3 wherein ~~a~~ an inexpensive visualization element and/or a display is electrically integrated on the surface substrate with the circuit.

8 (Currently amended). The circuit board ~~or substrate~~ arrangement as claimed in claim 7 wherein the display comprises electrochromic material, liquid crystalline elements and/or organic light-emitting diodes.

9 (Currently amended). The circuit board ~~or substrate~~ arrangement as claimed in claim 7 wherein a driver circuit associated with the display is electrically integrated on the surface substrate with the circuit.

10 (Currently amended). The circuit board ~~or substrate~~ arrangement of claim 9 ~~7~~ wherein ~~the a driver circuit electronics is included and~~ comprises at least one organic field-effect transistor.

11 (Currently amended). The use of the circuit board ~~or substrate~~ arrangement as claimed in one of claims 1 to 3 for an electronic device including any of a sensor label, an advertising ticket, a price marker, a game, a check card and an RFID tag.

12 (Currently amended). The circuit board ~~or-substrate~~ arrangement as claimed in claim 8 wherein a driver circuit associated with the display is electrically integrated on the surface with the display substrate.

13 (Currently amended). The circuit board ~~or-substrate~~ arrangement of claim 8 wherein a driver electronics is included and comprises at least one organic field-effect transistor coupled to the circuit.

14 (Currently amended). The circuit board ~~or-substrate~~ arrangement of any one of claims 1 or 2-9 wherein a driver electronics is included and comprises at least one organic field-effect transistor coupled to the circuit.

15 (Currently amended). The use of the circuit board ~~or-substrate~~ arrangement as claimed in claim 4 for an electronic device including any of a sensor label, an advertising ticket, a price marker, a game, a check card and an RFID tag.

16 (Currently amended). The use of the circuit board ~~or-substrate~~ arrangement as claimed in claim 5 for an electronic device including any of a sensor label, an advertising ticket, a price marker, a game, a check card and an RFID tag.

17 (Currently amended). The use of the circuit board ~~or-substrate~~ arrangement as

claimed in claim 6 for an electronic device including any of a sensor label, an advertising ticket, a price marker, a game, a check card and an RFID tag.

18 (Currently amended). The use of the circuit board ~~or substrate~~ arrangement as claimed in claim 7 for an electronic device including any of a sensor label, an advertising ticket, a price marker, a game, a check card and an RFID tag.

19 (Currently amended). The use of the circuit board ~~or substrate~~ arrangement as claimed in claim 8 for an electronic device including any of a sensor label, an advertising ticket, a price marker, a game, a check card and an RFID tag.

20 (Currently amended). The use of the circuit board ~~or substrate~~ arrangement as claimed in claim 9 for an electronic device including any of a sensor label, an advertising ticket, a price marker, a game, a check card and an RFID tag.

21 (Currently amended). The use of the circuit board ~~or substrate~~ arrangement as claimed in claim 10 for an electronic device including any of a sensor label, an advertising ticket, a price marker, a game, a check card and an RFID tag.